

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2634hmse-hmi8#pbf

(Engineering Calculation)

MSOP-Exposed

(printed on: 2020-07-11 21:59:23)

TOTAL MASS (g) : 0.027045

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001817 | 1000000 | 67184.2578125 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.010433 | 975000 | 385764.0625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000257 | 24000 | 9502.671875 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000003 | 300 | 110.926132202 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000007 | 700 | 258.827636719 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.010700 | 1000000 | 395636.53125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000710 | 1000000 | 26253.4394531 | | |
| | | External Plating Total: | | | | 0.000710 | 1000000 | 26253.4394531 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000086 | 1000000 | 3179.88208008 | | |
| Internal Plating Total: | | | | 0.000086 | 1000000 | 3179.88208008 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000644 | 750000 | 23812.140625 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000215 | 250000 | 7949.70507812 | | |
| Die Attach Total: | | | | 0.000859 | 1000000 | 31761.8476562 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001659 | 130000 | 61342.1445312 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.010591 | 830000 | 391606.21875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000447 | 35000 | 16527.9921875 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000064 | 5000 | 2366.42407227 | | |
| | | Encapsulation Total: | | | | 0.012761 | 1000000 | 471842.75 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000112 | 1000000 | 4141.2421875 | | |
| | | | | | TOTAL MASS (g) : | 0.027045 | | |